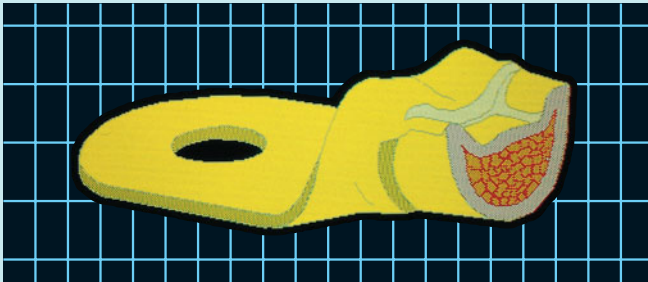
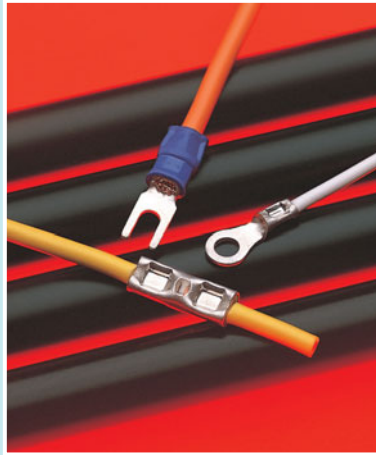
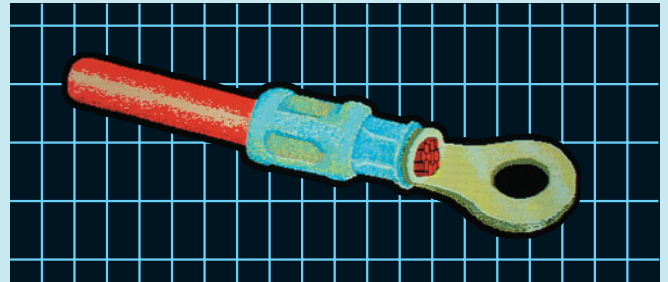


Crimping technology for JST solderless terminals.



“O” crimp method

The reliable "O" crimp developed by JST retains at least 75% of the conductor thickness along the entire length of the terminal. The special configuration of the crimping dies assures high retention of the terminal with minimal distortion of the wire cross section. Strong, low resistance termination of stranded, solid, or even flat conductors (or combined types) is assured.



“H” crimp method

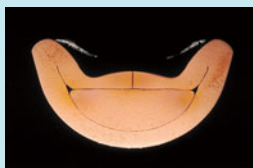
The "H" type crimp was specifically designed by JST for terminals with elongated insulations or copper sleeves. The longitudinal elongation of the insulation under high crimping pressure is absorbed to prevent rupture or uneven wall thickness.



Cross section of crimping of stranded wire



Cross section of crimping of flat wire



Cross section of crimping of solid wire

